AF Amdt entered

Amendments to the Claims:

1. (Currently amended) A screen ink printed film carrier, comprising a thin film carrier layer supporting an ink pattern containing an electrically resistive or conductive material and a curable resin, wherein said thin film carrier layer comprises a curable adhesive material in contact with said ink pattern, and the curable adhesive material being co-curable with the curable resin, wherein the screen ink printed film carrier has an overall density of about 0.05 to 0.1 lb/ft^3.

2. (Original) The screen ink printed film carrier of claim 1, wherein said thin film carrier layer comprises a fibrous sublayer and a continuous surface layer attached to said fibrous sublayer, said continuous surface layer comprising a thermosetting resin.

3. (Original) The screen ink printed film carrier of claim 2, wherein said fibrous sublayer is a textile material selected form the group consisting of a woven layer, a knit layer, a scrim layer, and a nonwoven layer.

4. (Original) The screen ink printed film carrier of claim 2, wherein said fibrous sublayer is a woven polyester.

5. (Original) The screen ink printed film carrier of claim 2, wherein said fibrous sublayer is selected from the group consisting of a polyester scrim and a nylon scrim.

6. (Currently Amended) The screen ink printed film carrier of claim 2, wherein said thin film carrier layer has an overall thickness of about ~~3~~ 6 to about 25 mils.

7. (Original) The screen ink printed film carrier of claim 2, wherein said thermosetting resin contained in said continuous surface layer is selected from the group consisting of an epoxy compound, a cyanate ester compound, and a phenolic compound.

8. (Original) The screen ink printed film carrier of claim 1, wherein said curable resin contained in said ink pattern comprises a thermosetting resin selected from the group consisting of phenolic, phenolic/epoxy mixtures, and polyimide.

9. (Original) The screen ink printed film carrier of claim 1, wherein said ink pattern is a hexagonal shaped pattern.

10. (Original) The screen ink printed film carrier of claim 1, wherein said ink pattern contains a conductive material selected from the group consisting of silver, nickel, copper, platinum, and palladium.

11. (Original) The screen ink printed film carrier of claim 1, wherein said ink pattern contains a magnetic material selected from the group consisting of iron and ferrites.

12 – 20. Cancelled.

21. (Previously presented) The screen ink printed film carrier of claim 2, wherein the fibrous sublayer has a thickness of about 125 to 380 μm, and the continuous surface layer has a thickness of about 25 to 250 μm.

22. (Previously presented) The screen ink printed film carrier of claim 2, wherein the thermosetting resin of the continuous surface layer comprises a B-stage resin.

23. (Previously presented) The screen ink printed film carrier of claim 22, wherein the thermosetting resin comprises an epoxy resin.

24. Canceled.

25. (Previously presented) The screen ink printed film carrier of claim 1, wherein the ink pattern maintains a resolution of 1 – 2 mm after curing of the screen ink printed film carrier.

26. (Currently amended) The screen ink printed film carrier of claim 22, wherein the thermosetting resin comprises an epoxy resin, and the ink pattern maintains a resolution of 1-2 mm after curing of the screen ink printed film carrier~~, and the screen ink printed film carrier has an overall density of about 0.05 to 0.1 lb/ft^3~~.

27. (Previously presented) The screen ink printed film carrier of claim 2, wherein the ink pattern comprises silver particles and a curable thermosetting resin.

28. (Previously presented) The screen ink printed film carrier of claim 1, wherein:

said thin film carrier layer comprises a fibrous sublayer and a continuous surface layer attached to said fibrous sublayer, said continuous surface layer comprising a thermosetting resin; and

said curable resin contained in said ink pattern comprises a thermosetting resin selected from the group consisting of phenolic, phenolic/epoxy mixtures, and polyimide.